

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	948	(dissolved:adj:oxygen) and (semiconductor or resist or photoresist)	USPAT	OR	OFF	2005/05/02 11:03
L2	283	1 and (fluorine or fluoric or hydrofluoric or fluoride)	USPAT	OR	OFF	2005/05/02 12:41
L3	283	1 and (fluorine or fluoric or hydrofluoric or fluoride)	USPAT	OR	OFF	2005/05/02 14:26
L4	16	((("5314725") or ("6331490") or ("6664197") or ("5424252") or ("6417112") or ("6638899") or ("6165912") or ("4112044") or ("6323169") or ("6767689") or ("5698503") or ("5308745") or ("5622919") or ("6368421") or ("6261745") or ("6554912"))).PN.	USPAT	OR	OFF	2005/05/02 16:01
L5	0	(us-20020032280-\$).did.	USPAT	OR	OFF	2005/05/02 16:01
L6	1	(us-20020032280-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/05/02 16:02
L7	1	("20020032280").PN.	US-PGPUB; USPAT	OR	OFF	2005/05/02 16:02
L8	7	((("5314725") or ("5698503") or ("6261745") or ("6323169") or ("6368421") or ("6554912") or ("6638899"))).PN.	USPAT	OR	OFF	2005/05/02 16:24
L9	158424	(solution or composition) and (fluorine or fluoride or fluoro or fluoric or hydrofluoric) not (peroxide or peroxygen)	USPAT	OR	OFF	2005/05/02 16:24

New Text Document.txt

Serial Number:
10601659
Pgpub Number:
0

Keywords:

code; ikemoto; kazuto; february; resist; resist
stripping; stripping; liquid; containing; fluorine; compound; abstract; concentration; disso
lved; dissolved oxygen; oxygen; ppm; residues; removed; substrate; copper; copper
alloy; alloy; causing; corrosion; inventors; tokyo; ohto; masaru; correspondence;

Class list:

510/176; 510/175; 134/3; 134/2; 510/255; 134/1.3; 134/41; 510/499; 134/42; 252/79.4;

Int Class list:

C11D 007/50; B08B 003/08; C11D 007/32; C23G 001/02; H01L 021/302; H01L 021/306; C11D
007/26; C11D 007/08; B08B 003/04; H01L 021/461;

Special Keywords:

strip; stripping; stripping photoresists; photoresist; DMSO; glycol ether; dissolved
oxygen;

Negative Keywords:

dishwashing; CMP; polishing; peroxide; hydrogen peroxide; peroxygen;

Features:

feature#1(w=200); fluorine compound; hydrofluoric; fluoride; fluorine;
feature#2(w=200); dissolved oxygen; deionized water; DI water; ultrapure water;
feature#3(w=100); preferred solvent; ethylene glycol monoethyl ether; ethylene glycol
monobutyl ether; diethylene glycol monomethyl ether; diethylene glycol monoethyl
ether; diethylene glycol monobutyl ether; triethylene glycol; triethylene glycol
monomethyl ether; triethylene glycol monoethyl ether; triethylene glycol monopropyl
ether; triethylene glycol monobutyl ether; triethylene glycol dimethyl ether; propylene
glycol monomethyl ether; propylene glycol monoethyl ether; propylene glycol monobutyl
ether; dipropylene glycol monomethyl ether; dipropylene glycol monoethyl
ether; dipropylene glycol monobutyl ether; diethylene glycol dimethyl
ether; dipropylene glycol dimethyl
ether; formamide; monomethylformamide; dimethylformamide; monoethylformamide; diethylform
amide; acetamide; monomethylacetamide; dimethylacetamide; monoethylacetamide; diethylacet
amide; N-methylpyrrolidone; N-ethylpyrrolidone; N-methylcaprolactam; methyl
alcohol; ethyl alcohol; isopropanol; ethylene glycol; propylene glycol; dimethyl
sulfoxide; dimethylsulfone; diethyl sulfone; bis(2-hydroxyethyl) sulfone; tetramethylene
sulfone; 1,3-dimethyl-2-imidazolidinone; 1,3-diethyl-2-imidazolidinone; 1,3-diisopropyl
-2-imidazolidinone; .gamma.-butyrolactone; .delta.-valerolactone; aminoethanol; diethano
lamine; triethanolamine; isopropanolamine; 1-amino-3-propanol; diisopropanolamine; triiso
propanolamine; dimethylaminoethanol; N-methylaminoethanol; diethylaminoethanol; aminoeth
oxyethanol; ethylenediamine; diethylenetriamine; triethylenetetramine; tetraethylenepent
amine;
feature#4(w=600); preferred fluorinated compound; ammonium fluoride; acid ammonium
fluoride; hydrofluoric acid; hydrofluoric; fluoric;
feature#5(w=200); method for removing resists; photoresist; resist;
feature#6(w=100); copper and/or; copper alloy; copper; copper alloy; copper oxide;